

Integrated circuit smart card with part floating support for semiconductor

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Abstract of FR2745930

The card has a card body (1) with an integrated circuit (2) set in a recess in the body. The integrated circuit is connected by conductive tracks (4) to contact pads on the surface of the card. Grooves (6,8) formed in the card body extend between the contact pads and the integrated circuit, forming lines that absorb bending stress so it is not transmitted to the integrated circuit. Immediately above the integrated circuit a 'U'-shaped groove (12) combines reduction of stress on integrated circuit with stress reduction on conductors from integrated circuit.

